

ABSTRACT OF THE DISCLOSURE

A flexible wiring board is obtained as follows. A copper foil pattern is formed on the both surfaces of a base polymer film made of polyimide, etc. The copper foil pattern of the both sides, except for an end portion of the copper foil pattern of one surface, is covered entirely with an insulative protecting film made of polyimide, etc., for protecting the copper foil pattern, and the insulative protecting film and the copper foil pattern are bonded with each other by an insulative protecting film adhesive layer. On the exposed end portion of the copper foil pattern on one surface is formed a plated layer to be connected to an electrical component. The thickness of the insulative protecting film which is bonded with the surface on which the plated layer is formed is set to be thinner than the base polymer film. As a result, it is ensured that insulation failure of the insulative protecting film is prevented, and wire breakage of wiring when bent can easily be prevented.

09712227 1150